

SOT1315-1

plastic low profile fine-pitch ball grid array package; 170 balls

8 June 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA170
Package type industry code	LFBGA170
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-205
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	4-11-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	1.25	-	1.35	1.5	mm
A ₂	package height	0.95	-	1	1.1	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	170	-	



2. Package outline

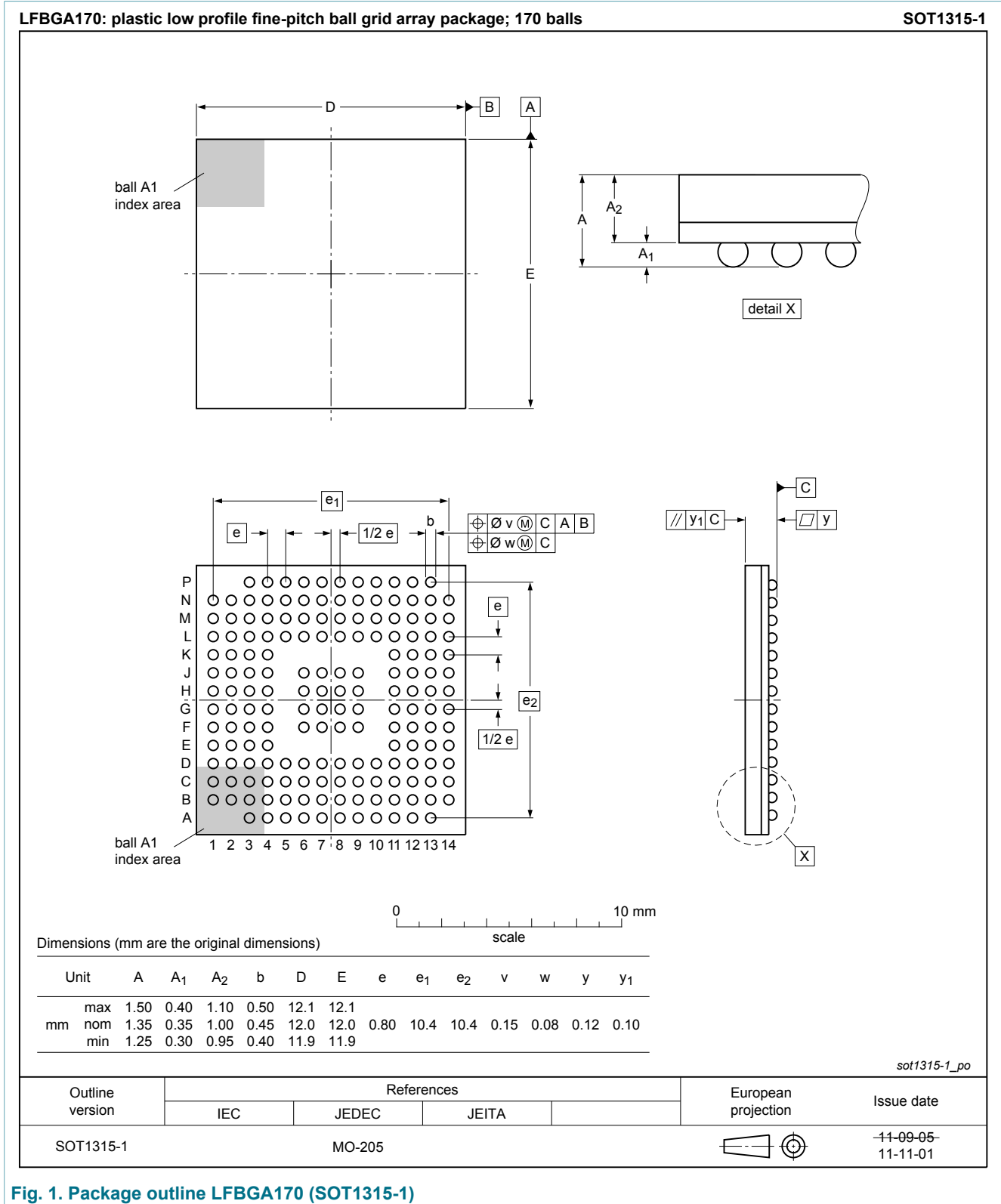
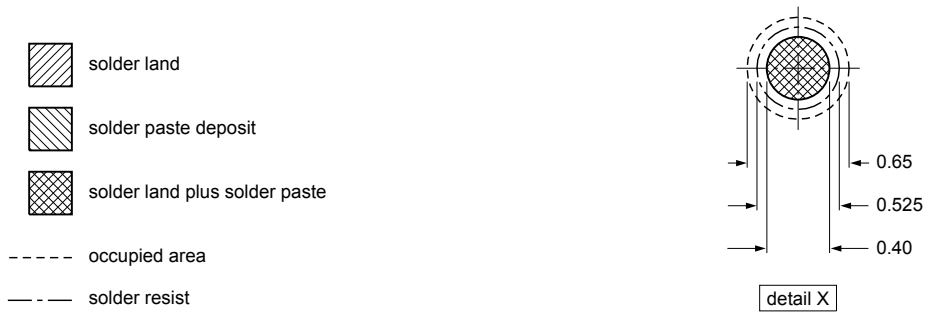
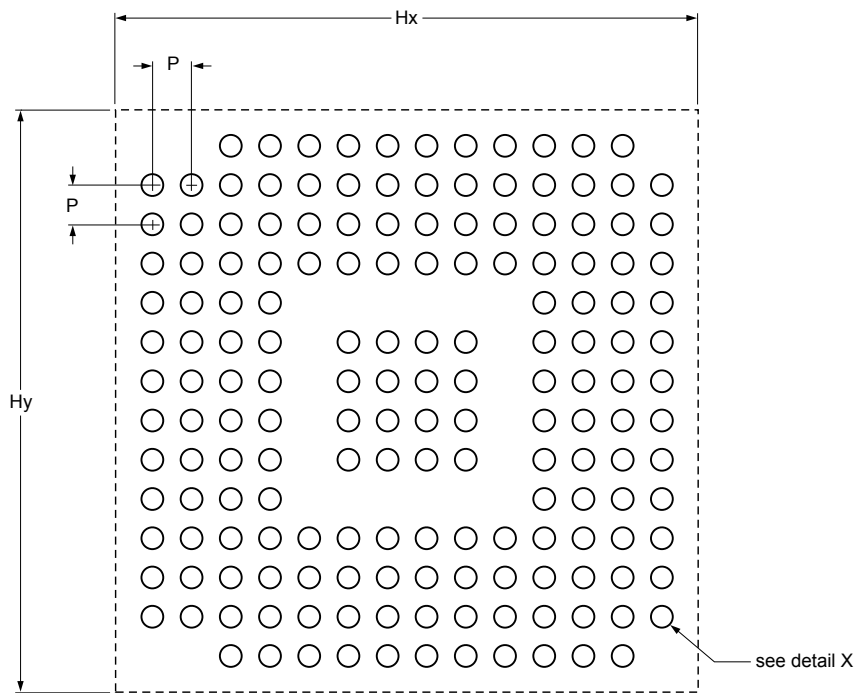


Fig. 1. Package outline LFBGA170 (SOT1315-1)

3. Soldering

Footprint information for reflow soldering of LFBGA170 package

SOT1315-1



Dimensions in mm

P	Hx	Hy
0.80	12.0	12.0

sot1315-1_fr

Fig. 2. Reflow soldering footprint for LFBGA170 (SOT1315-1)

4. Legal information

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